

ABSTRACT OF DISCLOSURE
PACKING MATERIAL FOR WAFER

A packing material for wafer packed up by stacking up a plurality of wafers, includes a protective sheet protecting an optical surface being glued to an entire upper surface of the wafer; a dicing tape being concurrently glued to an entire lower surface of the wafer; and a first buffer being inserted in between each of the plurality of wafers and stacked up, whereafter both ends being protected with a second buffer.

Fig. 1A